

L Number	Hits	Search Text	DB	Time stamp
1	629468	flipchip (flip adj chip) bump ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 14:16
2	373139	heat with (sink spreader radiate dissipate slug metal cover lid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 14:17
3	9817	wires and (flipchip (flip adj chip) bump ball) and (heat with (sink spreader radiate dissipate slug metal cover lid))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 14:17
4	967	wires same (flipchip (flip adj chip) bump ball) same (heat with (sink spreader radiate dissipate slug metal cover lid))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 14:17
5	788	(carrier substrate board) and (wires same (flipchip (flip adj chip) bump ball) same (heat with (sink spreader radiate dissipate slug metal cover lid)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 14:18
6	662	((carrier substrate board) and (wires same (flipchip (flip adj chip) bump ball) same (heat with (sink spreader radiate dissipate slug metal cover lid))) and (package packaged packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 14:18